

S01P0052US00 6640/63437

DECLARATION AND POWER OF ATTORNEY

As a below-named inventor, I hereby declare that:

Japan

My residence, post office address, and citizenship are as stated below next to my name.

			•	•
I believe I am the originatinventor (if plu patent is sought on the	ral names	are listed below	r (if only one na	nme is listed below) or an original, first and t matter which is claimed and for which a
		HEADPHON	NE DEVICE	
the specification of w (check one)	hich			
	_	is attached he	reto.	
	<u>X</u>	was filed on_	12/28/00	(International Filing Date) as
	Intern	ational Applicat	tion No	
	corres	sponding to		
	and v	vas amended on		(if applicable)
I acknowledge the do of this application in I hereby claim force application(s) for pa	, as amend uty to discl accordan ign priorit	led by any amen lose information ce with Title 37, y benefits under ventor's certifica	of which I am Code of Feder Title 35, Unit	attents of the above-identified specification to above. aware which is material to the examination al Regulations, Section 1.56(a). ed States Code, Section 119 of any foreign and have also identified below any foreign date before that of the application on which
Prior Foreign Appli	cation(s)			Priority Claimed
Number	Coun	try	Filing Date	<u>Xes</u> <u>No</u>

January 7, 2000

Declaration and Power of Attorney

Application Serial No.

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I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States Application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Filing Date

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And I hereby appoint Jay H. Maioli, Reg. No. 27,213; Donald S. Dowden, Reg. No. 20,701; William E. Petton, Reg. No. 25,702; Peter J. Phillips, Reg. No. 29,691; Gerald W. Griffin, Reg. No. 18,886; Ivan S. Kavrukov, Reg. No. 25,161; Christopher C. Dunham, Reg. No. 22,031; Norman H. Zivin, Reg. No. 25,385; John P. White, Reg. No. 28,678; and Robert D. Katz, Reg. No. 30,141; and each and all of them, all c/o Cooper & Dunham, 1185 Avenue of the Americas, New York, NY 10036 (Tel. (212) 278-0400), my attorneys, each with full power of substitution and revocation, to receive the patent, to transact all business in the Patent and Trademark Office connected therewith and to file any International Applications which are based thereon under the provisions of the Patent Cooperation Treaty.

Please address all communications, and direct all telephone calls, regarding this application to

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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